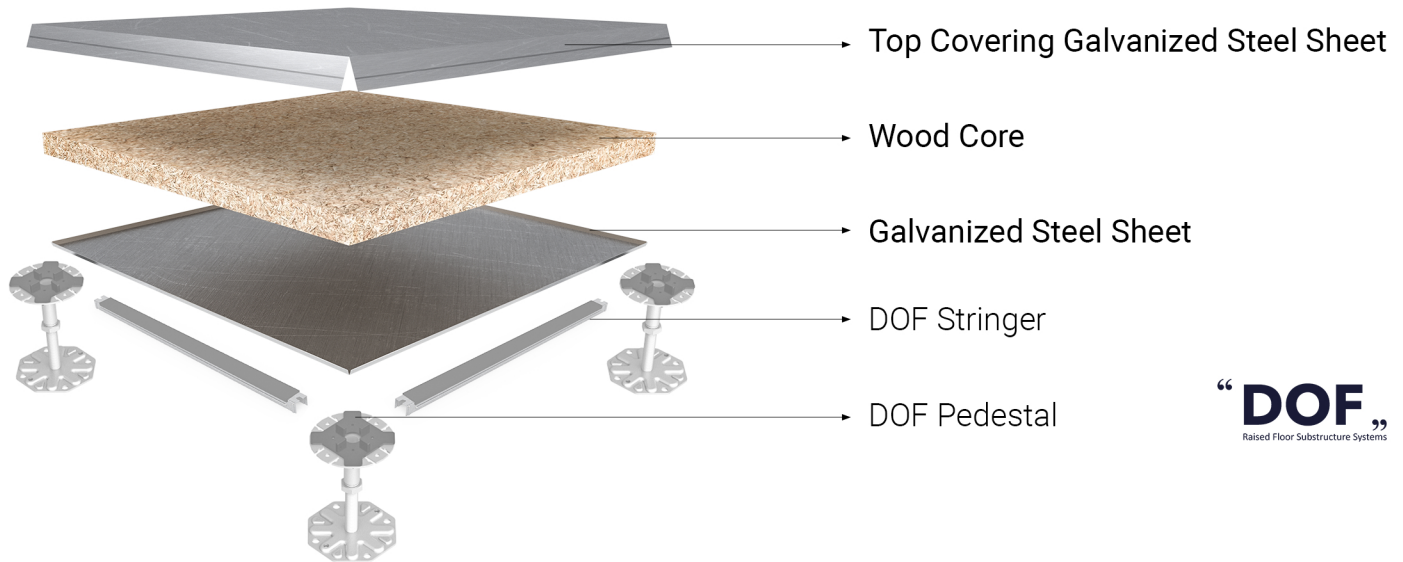


ENCAPSULATED WOOD CORE PANEL



“DOF”
Raised Floor Substructure Systems

TECHNICAL DATA

Thickness	: 30 mm
Weight	: ~ 8 - 9 kg
Panel Size	: 600 mm x 600 mm x 30 mm
Core Material	: 29 mm Chipboard Core
Panel Fire Reaction	: B1 Class according to EN 13501-1
Panel Fire Resistance	: REI60
System Sound Airborne Insulation $D_{n,f,w}(C;Ctr)$: 45 dB
System Sound Impact Insulation $L_{n,f,w}(CI)$: 66 dB

LOAD CARRYING CAPACITY

Type	Concentrated Load	Impact Load	Ultimate Load	Uniform Load	Rolling Road	
	(N)	(N)	(N)	(N/m ²)	10 Passes (N)	10000 Passes (N)
DF-W01	≥3550	538	≥10700	≥17000	3560	2670